

SOT650-3(DD)

HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

13 November 2025

Package information



1 Package summary

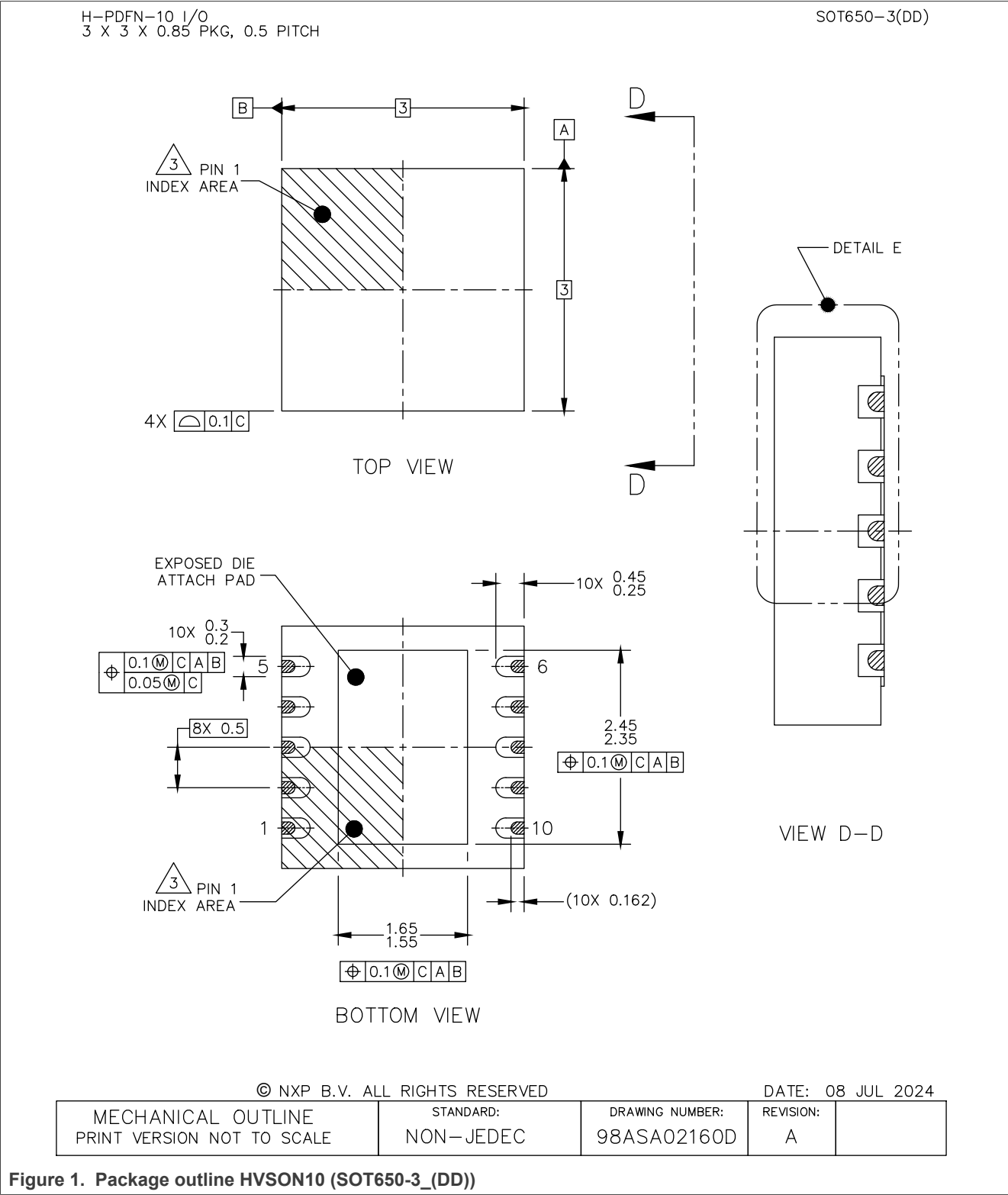
Terminal position code	D (double)
Package type descriptive code	HVSON10
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-11-2025
Manufacturer package code	98ASA02160D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	10	-	

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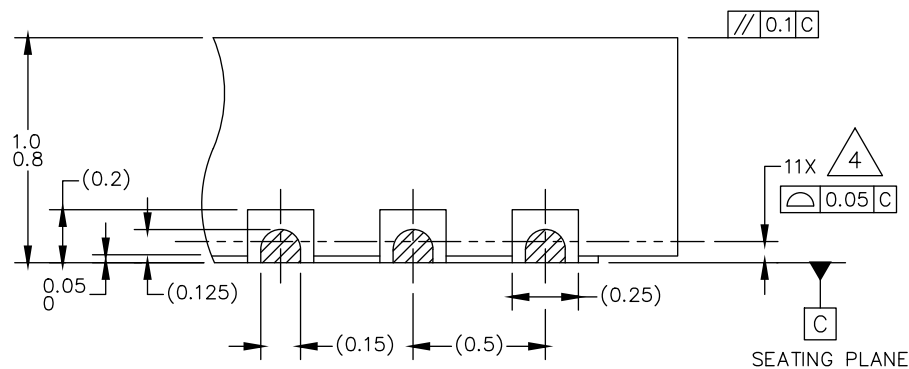
2 Package outline



HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

H-PDFN-10 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT650-3(DD)



DETAIL E
VIEW ROTATED 90° CW

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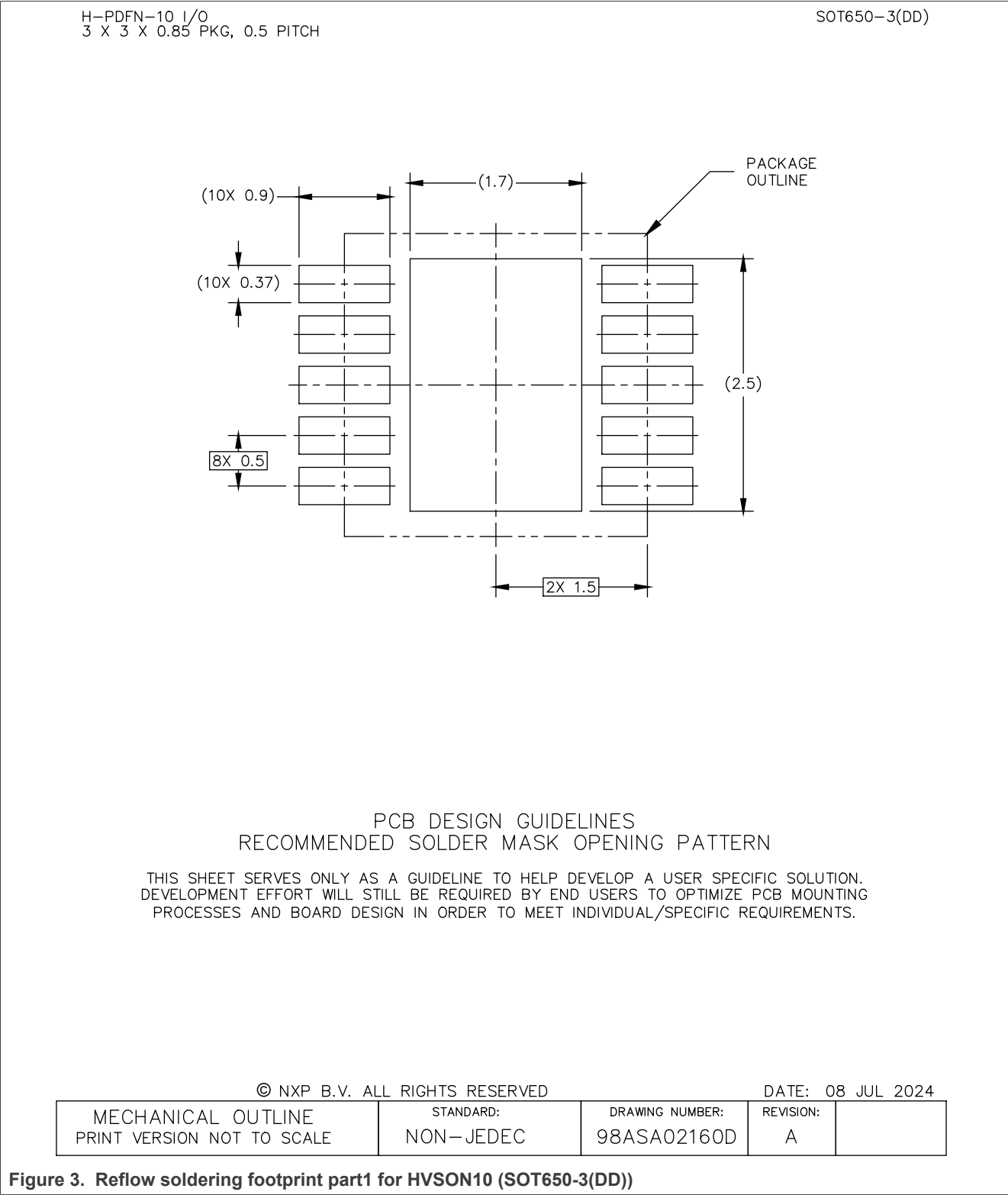
DATE: 08 JUL 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02160D	REVISION: A	
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Figure 2. Package outline detail E of HVSON10 (SOT650-3(DD))

HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

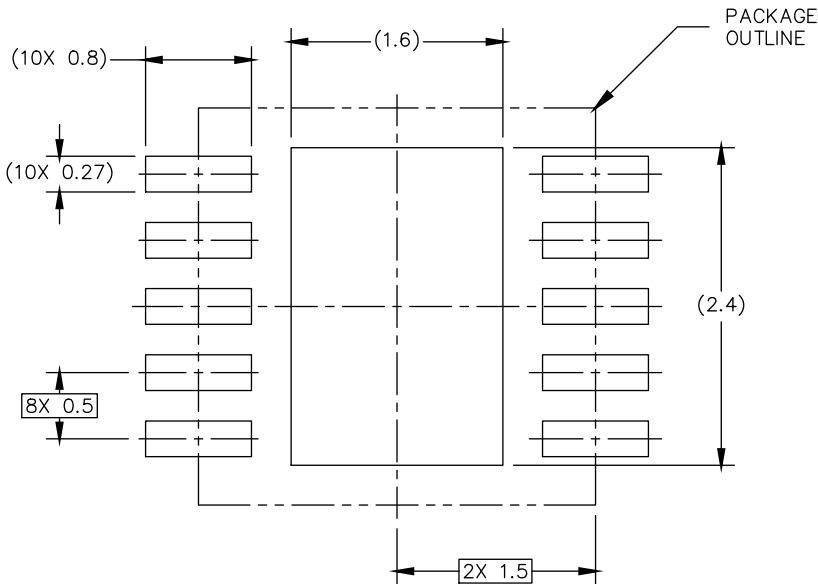
3 Soldering



HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

H-PDFN-10 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT650-3(DD)



PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 08 JUL 2024

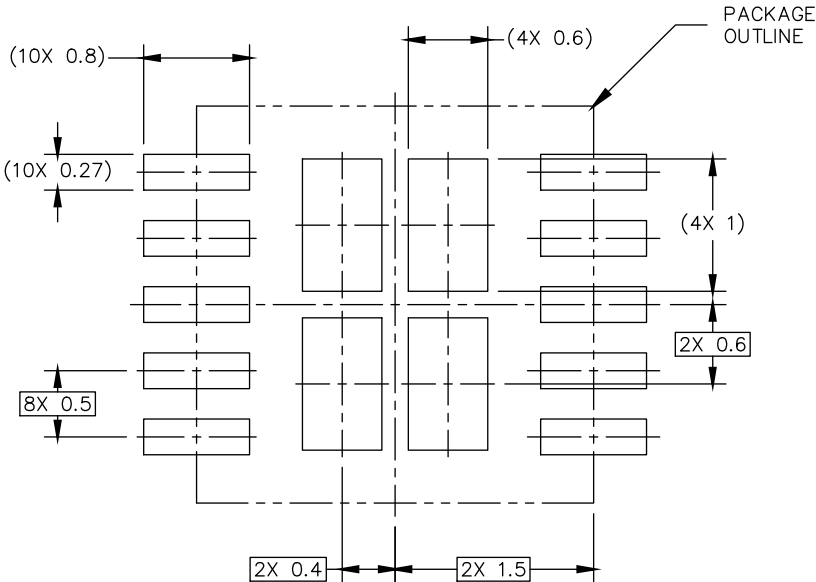
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02160D	REVISION: A	
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Figure 4. Reflow soldering footprint part2 for HVSON10 (SOT650-3(DD))

HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

H-PDFN-10 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT650-3(DD)



RECOMMENDED STENCIL THICKNESS 0.100

PCB DESIGN GUIDELINES – RECOMMENDED SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 5. Reflow soldering footprint part3 for HVSON10 (SOT650-3(DD))

HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

H-PDFN-10 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT650-3(DD)

- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
 - 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVSON10 (SOT650-3(DD))

HVSON10, thermal enhanced very thin small outline; no leads, 10 terminals, 0.5 mm pitch, 3 mm x 3 mm x 0.85 mm body

4 Legal information

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